Materials Declaration

Package	LQFP
Body Size	7 X 7
LeadCount	32
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	86	5.32 E-02	383516
Epoxy resin	8	4.94 E-03	35676
Phenol Resin	5	3.09 E-03	22297
Sb2O3	0.4	2.47 E-04	1784
Brominated Resin	0.4	2.47 E-04	1784
Carbon Black	0.2	1.24 E-04	892

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	5.11 E-02	368502
Ni	3	1.59 E-03	11492
Si	0.65	3.45 E-04	2490
Mg	0.15	7.96 E-05	575

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	8.00 E-04	5772

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	1.67 E-03	12025

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	8.81 E-04	6357

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.85 E-02	133601

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	4.77 E-04	3442
Ag Filler	74	1.36 E-03	9796

Molding Compound

Item	PPM	Method
Pb	None Detected	US EPA 3052. Analysis was performed by ICP-OES
Cd	None Detected	US EPA 3052. Analysis was performed by ICP-OES
Hg	None Detected	US EPA 3052. Analysis was performed by ICP-OES
Cr+6	None Detected	EPA 3060A & 7196A. Analysis was performed by UV-VIS.
PBB	None Detected	Analysis by GC/MS
PBDE	None Detected	Analysis by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	3.00	US EPA 3052. Analysis was performed by ICP-OES
Cd	None Detected	US EPA 3052. Analysis was performed by ICP-OES
Hg	None Detected	US EPA 3052. Analysis was performed by ICP-OES
Cr+6	None Detected	EPA 3060A & 7196A. Analysis was performed by UV-VIS.
PBB	None Detected	Analysis by GC/MS
PBDE	None Detected	Analysis by GC/MS

Package Totals

Weight (g)	PPM
1.39 E-01	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

Materials Declaration

Package	LQFP
Body Size	7 X 7
LeadCount	32
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	86.0	5.32 E-02	383516
Epoxy resin	8.0	4.94 E-03	35676
Phenol Resin	5.0	3.09 E-03	22297
Sb2O3	0.4	2.47 E-04	1784
Brominated Resin	0.4	2.47 E-04	1784
Carbon Black	0.2	1.24 E-04	892

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.20	5.11 E-02	368502
Ni	3.00	1.59 E-03	11492
Si	0.65	3.45 E-04	2490
Mg	0.15	7.96 E-05	575

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	8.00 E-04	5772

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	1.42 E-03	10222
Pb	15	2.50 E-04	1804

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	8.81 E-04	6357

Chip

	% of Chip	Weight (g)	PPM
Si	100	1.85 E-02	133601

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	26	4.77 E-04	3442
Ag Filler	74	1.36 E-03	9796

Package Totals

Weight (g)	PPM
1.39 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	None Detected	US EPA 3052. Analysis was performed by ICP-OES
Cd	None Detected	US EPA 3052. Analysis was performed by ICP-OES
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Cr+6	None Detected	EPA 3060A & 7196A. Analysis was performed by UV-VIS.
PBB	None Detected	Analysis by GC/MS
PBDE	None Detected	Analysis by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	3.00	US EPA 3052. Analysis was performed by ICP-OES
Cd	None Detected	US EPA 3052. Analysis was performed by ICP-OES
Hg	None Detected	US EPA 3052. Analysis was performed by ICP-OES
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ANALOG DEVICES

ADI Proprietary

09/06/06